AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in this application.

1.(Previously Presented) A method according to claim 42, wherein the article comprises a housing for a mobile telephone having electronic components; and

wherein applying the metallic material to the seeding substance on the carrier material comprises forming a metallic pattern for at least one electrical connection for electronic components of the mobile telephone.

2.(Currently Amended) A method according to claim 42, wherein the carrier material is an ink and is applied to the thermoplastic substrate by printing.

3.(Canceled)

4.(Currently Amended) A method according to ~~claim 3~~ claim 42, wherein ~~the step of~~ molding the thermoplastic substrate comprises stretching the thermoplastic substrate, wherein the binder material is selected from materials capable of stretching to at least the same extent as the thermoplastic substrate.

5.(Canceled)

6.(Previously Presented) A method according to claim 42, wherein the seeding substance comprises a plurality of metal particles in the carrier material.

7.(Previously Presented) A method according to claim 6, wherein the step of applying the metallic material to the seeding substance on the carrier material comprises plating the metallic material onto the metal particles in the carrier material.

8.(Previously Presented) A method according to claim 7, wherein the step of plating the metallic material onto the metal particles comprises at least one of electroplating and electroless plating.

9.(Original) A method according to claim 6, wherein the metal particles are present in a

range of 0.005 wt% to 10 wt%.

10.(Original) A method according to claim 6, wherein the metal particles are present in a range of 0.05 wt% to 5 wt%.

11.(Original) A method according to claim 6, wherein the metal particles are present in a range of 0.1 wt% to 2 wt%.

12.(Original) A method according to claim 6, wherein the metal particles have an average size of no greater than 0.15 μm.

13.(Original) A method according to claim 6, wherein the metal particles have an average size in the range of 0.003 μm to 0.05 μm.

14.(Original) A method according to claim 6, wherein the metal particles have an average size in the range of 0.003 μm to 0.015 μm.

15.(Currently Amended) A method according to claim 42, wherein the step of moulding the thermoplastic substrate comprises press moulding the substrate to form the moulded substrate.

16.(Currently Amended) A method according to claim 42, wherein the thermoplastic substrate comprises a plastic sheet.

17.(Canceled)

18.(Currently Amended) A method according to claim 42, wherein the step of molding the thermoplastic substrate is carried out before the step of applying the metallic material to the carrier material.

19.(Previously Presented) A method according to claim 42, wherein the pattern is a line pattern to define electrical connections.

20-41.(Canceled)

42.(Currently Amended) A method of forming a pattern on an article comprising:

applying a carrier material to a thermoplastic substrate to provide a pattern, the carrier material carrying a seeding substance to allow application of a metallic material thereto and a binder material for fixing the seeding substance on the substrate;

molding the thermoplastic substrate to form the article; and

applying the metallic material to the seeding substance on the carrier material,

wherein the binder material is one or more selected from the group consisting of acrylic resins, silicone, polyurethanes, polycarbonates, polyesters, rubbers, polyimides, polyolefins, derivatives of polyolefins, polystyrenes, derivatives of polystyrenes and polymer alloys.

43.(Previously Presented) The method of claim 42, wherein the binder material comprises a polymer alloy selected from the group acrylonitrile-butadiene-styrene and acrylstyrene.

44-50.(Canceled)